

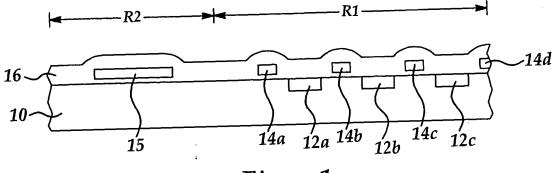
Inventor(s): Chen, et al Serial No.: To Be Assigned

Filed: Herewith

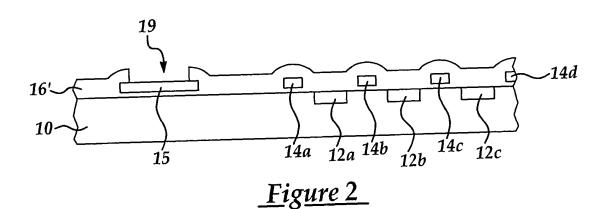
For: Microelectronic Fabrication With Corrosion Inhibited Bond Pad

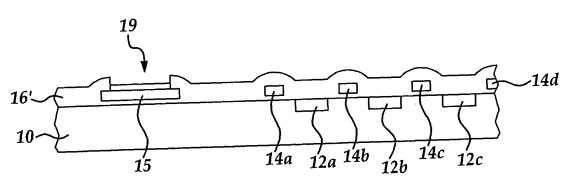
Attorney Docket No.: 67,200-571

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<u>Figure 1</u>





<u>Figure 3</u>

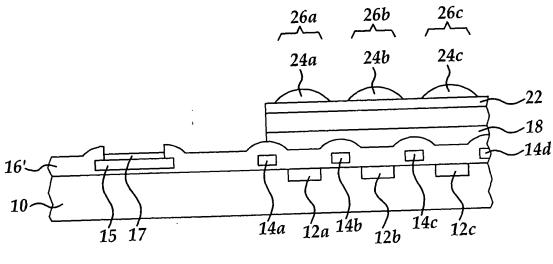
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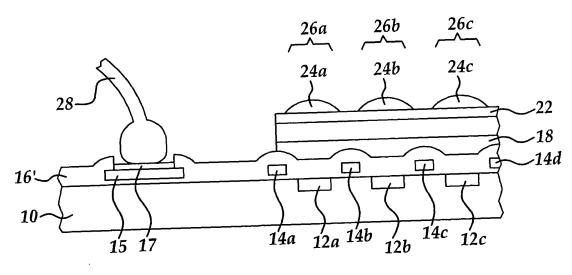
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<u>Figure 4</u>



<u>Figure 5</u>